

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5067240

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SHIH-WEI HUNG	09/30/2016
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	NO 8, LI-HSIN RD. 6	
Internal Address:	HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16045415
CORRESPONDENCE DATA		
Fax Number:	(214)200-0853	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	214-651-5000	
Email:	ipdocketing@haynesboone.com	
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION	
Address Line 1:	2323 VICTORY AVENUE	
Address Line 2:	SUITE 700	
Address Line 4:	DALLAS, TEXAS 75219	
ATTORNEY DOCKET NUMBER:	2015-1401/24061.3340US02	
NAME OF SUBMITTER:	LINDA INGRAM	
SIGNATURE:	/Linda Ingram/	
DATE SIGNED:	07/25/2018	
Total Attachments: 2		
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source=3340US02_Assignment#page2.tif		

ASSIGNMENT

WHEREAS, I,

(1) Shih-Wei Hung of Hsin-Chu, Taiwan, Republic of China

have invented certain improvements in

THERMAL REFLECTOR DEVICE FOR SEMICONDUCTOR FABRICATION TOOL

for which I have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on October 6, 2016, and assigned application number 15/287,434; and

WHEREAS, I authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: P20151401US00/24061.3340US01
Customer No.: 000042717

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shih-Wei Hung

Residence Address: No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
Hsin-Chu, Taiwan 300-77, Republic of China

Dated: 2016/9/30

SHIH-WEI HUNG
Inventor Signature
